PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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Assignment ID: PATI283088

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mr. Zvi Or-Bach	05/31/2024
Mr. Brian Cronquist	05/31/2024
Dr. Deepak C. Sekar	06/06/2024

RECEIVING PARTY DATA

Company Name:	Monolithic 3D Inc.
Street Address:	1662 Cove Point Road
City:	Klamath Falls
State/Country:	OREGON
Postal Code:	97601-9300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18736423

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone:	4088399533
Email:	Brian@MonolithIC3D.com
Correspondent Name:	Mr. Brian Cronquist
Address Line 1:	1662 Cove Point Road
Address Line 4:	Klamath Falls, OREGON 97601-9300

ATTORNEY DOCKET NUMBER:	M3D-15HBVN_40con12
NAME OF SUBMITTER:	Brian Cronquist
SIGNATURE:	Brian Cronquist
DATE SIGNED:	06/06/2024

Total Attachments: 3
source=M3D-15HBVN_40con12_Assignment_Zvi---signed#page1.tif
source=M3D-15HBVN_40con12_Assignment_Brian---signed#page1.tif
source=M3D-15HBVN_40con12_Assignment_Deepak---signed#page1.tif

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH METAL LAYERS AND MEMORY CELLS

as described in U.S. Patent Application Serial No. 18/tbd and filed on or about June 01, 2024; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

צבי אור-בך

DATE on 05 / 31 / 2024

(Zvi		**Or-Bach)**
First Name	Middle Initial	Last Name

ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in Klamath Falls, Oregon;** have made a certain invention, and United States Patent Application entitled:

3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH METAL LAYERS AND MEMORY CELLS

as described in U.S. Patent Application Serial No. 18/tbd and filed on or about June 01, 2024; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

Brian Cronquist

DATE on 05 / 31 / 2024

(Brian **Cronquist)**

First Name Middle Initial Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and United States Patent Application entitled:

3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH METAL LAYERS AND MEMORY CELLS

as described in U.S. Patent Application Serial No. 18/tbd and filed on or about Jun 01, 2024; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 06 / 06 / 2024

(Deepak		**Sekar)**
First Name	Middle Initial	Last Name